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Substitute for form 1449A/PTO		<b>Complete if Known</b>	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		Application Number	10/058,557
		Filing Date	01/28/02
		First Named Inventor	Chen et al.
		Group Art Unit	2812
		Examiner Name	Unknown
Sheet	1	of	2
		Attorney Docket Number	AP01983

**U. S. PATENT DOCUMENTS**

U. S. PATENT DOCUMENTS						
Examiner Initials*	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code <sup>2</sup> (if known)			
JML		3,761,784		Jund	07/04/1989	
		4,191,057		Busta	05/27/1997	
		4,275,406		Muller et al.	06/23/81	
		4,317,126		Gragg, Jr.	02/23/82	
		4,395,451		Althouse	07/26/83	
		4,444,054		Schaff, Jr	04/24/84	
		4,667,944		Althouse	05/26/87	
		4,683,755		Samek	08/04/87	
		4,711,014		Althouse	12/08/87	
		4,986,861		Nishida et al.	01/22/91	
		4,996,627		Zias et al.	02/26/91	
		5,356,176		Wells	10/18/94	
		5,629,486		Viduya et al.	05/13/97	
		5,644,102		Rostoker	07/01/97	
JML		5,917,264		Maruno et al.	06/29/99	

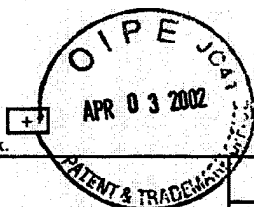
**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>6</sup>
		Office <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>2</sup> (if known)				

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OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS		
Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
JMM		"Micromachines on the March" Janusz Bryzek, Kurt Petersen, and Wendell McCulley. IEEE Spectur, May 1994, pp 20-31.
		"Ultra Thin ICs Open New Dimensions for Microelectric Systems" G. Klink, C. Landesberger, M. Feil, F. Ansorge, R. Aschenbrenner. Advancing Microelectronics, July/August 2000; pp.23-25.
		"New Process Scheme for Wafer Thinning and Stress-free Separation of Ultra Thin ICs" C. Landesberger, S. Scherbaum, G. Schwinn, H. Spohrle. Proceedings of Microsystems Technologies 2001; pp.1-7.
		"Innovative Packaging Concepts for Ultra Thin Integrated Circuits" G. Klink, M. Feil, F. Ansorge, R. Aschenbrenner, H. Reichl. Electronic Components and Technology Conference, 2001; pp. 1034-1039.
		"Thin Silicon Chips and ACF Connection Technology for Contactless IC Cards" Mitsuo Usami. 1999 International Symposium on Microelectronics; pp. 309-312.
		"Mechanical Lapping, Handling and Transfer of Ultra-Thin Wafers" S. Pinel, J. Tasselli, J.P. Bailbe, A. Marty, P. Puech and D. Esteve. Microengineering Vol. 8, 1998; pp 338-342.
		"SmartCard Assembly Requires Advanced pre-Assembly Methods" Dr. J. Muller, P. Stampka, W. Kruninger, E. Gaulhofer, H. Oyrer. Semiconductor International, July 2000; pp. 191-200.
		"Thin Monocrystalline Silicon Films on Flexible Substrates Enable Multiple Transfer Processes" C. berge, Dr. R. Bergmann, D. J. Werner. MRS Bulletin, August 2001; pp. 603.
		Khazan, A.D., "Transducers and Their Elements: Design and Application." Prentice-Hall, Inc. 1994, ISBN 03-13-929480-5. pp 393-395.
JMM		"Packaging Very High Pressure Transducers for Common Rail Diesel Injection Systems" K. Sidhu, Measurement Specialties, Inc. October 1987, pp. 1-4

Examiner Signature	<i>[Signature]</i>	Date Considered	3/5/03
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